

(1,00mm) .03937"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

Mates with:
 (0,80mm) .031" PCB,
 (1,60mm) .062" PCB

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material: Black LCP
Contact Material: BeCu
Plating: Sn or Au over 50µ" (1,27µm) Ni
Operating Temp Range: -55°C to +125°C
Insertion Depth: (5,26mm) .207" to (6,10mm) .240"
RoHS Compliant: Yes

Processing:
Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10mm) .004" max (20-30)
 (0,15mm) .006" max (40-50)

Important Note:
 Samtec recommends that pads on the mating board be Gold plated.

Note: Other Gold plating options available. Contact Samtec.

Note:
 Some sizes, styles and options are non-standard, non-returnable.

MB1
1
NO. OF PINS
01
PLATING OPTION
S
CARD SLOT
SL
OTHER OPTION

20, 30, 40, 50

-F
= Gold flash on contact, Matte Tin on tail

-L
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

Specify CARD SLOT from chart

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0,97) .038	(0,80) .031
-02	(1,83) .072	(1,60) .062

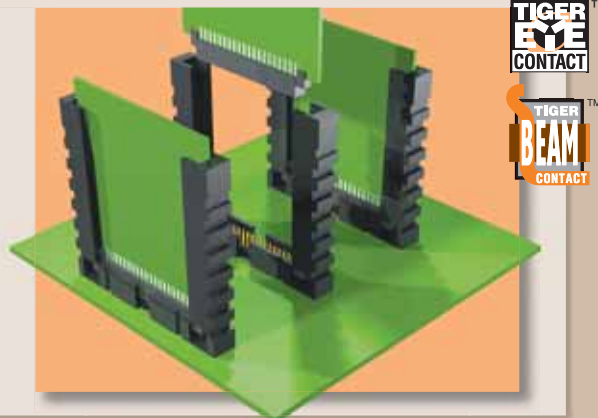
-N OPTION

-N
= No Card Guides

ALSO AVAILABLE

Flex Card System

- 2mm (.0787") (FCT/EMT Series) and .050" (1,27mm) (FCF/EMF Series) systems
- Vertical and horizontal
- Header with snap-on card guides for design flexibility
- Elevated design now available
- PCMCIA (PCMT/PCMS Series) Compact Flash (CFT/CFS Series) compatible applications available
- Ideal for multiple add-on cards
- Solder locks for mechanical stability
- Any size from 40 to 100 contacts



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM